# Curriculum & Syllabi

# of

# **Master of Technology**

In

# Digital System (w.e.f. 2018-19)

Vision Mission Program Educational Objectives Program Outcomes Program Specific Outcomes Overall Credit Structure Curriculum Syllabus



**Offered** By

ELECTRONICS AND COMMUNICATION ENGINEERING DEPARTMENT M. M. M. UNIVERSITY OF TECHNOLOGY, GORAKHPUR-273010, UP August 2021

## Department of Electronics and Communication Engineering CURRICULA & SYLLABI M. Tech. Digital System

## Vision:

To become a leader of education, research and innovation in the area of Electronics and Communication Engineering and to train students to be innovative and well prepared professionals in the area of Electronics and Communication Engineering.

## **Mission:**

- 1. Educate and mentor students to meet the current as well as future challenges by providing them with a firm foundation in both theory and practice of Electronics and Communication Engineering.
- 2. Create, develop and disseminate new knowledge by top quality applied research in Electronics and Communication Engineering by interacting with government agencies and private industry.
- 3. Promote a sense of leadership and service to the society.

## **Program Educational Objectives (PEOs)**

- PEO-1: To enable students in digital systems engineering with experts and professionals in the present generation of advanced digital techniques.
- PEO-2: To develop the capability of independent research project in digital systems engineering applying research principles and methods.
- PEO-3: To train the post-graduate in digital systems with the depth knowledge of various subjects of state-of-art interest.
- PEO-4: To train the postgraduate having the knowledge of different simulation tools used for measure the performance and diagnose the digital systems.
- PEO-5: To prepare students for Compiling and interpreting research data and presenting them in an appropriate format with scientific presentation, taking into consideration scientific principles and methodology, as well as practical applicability.
- PEO-6: To train students a high level of autonomy, accountability, credibility, ethics, and responsibility for all personal work outputs in the advanced digital domain.

## **Programs Outcomes (POs)**

M.Tech. Digital System students will demonstrate the ability to:

- PO-1 An ability to understand concept of advanced digital systems challenges and problems.
- PO-2 Educate and mentor students to address future challenges.
- PO-3 An ability to independently carry out research /investigation and development work to solve practical problems.
- PO-4 Design and implement an independent research project in field of digital systems by applying research principles and methods.
- PO-5 Create, develop and disseminates new knowledge in the field of digital systems.
- PO-6 Recognise the need for life- long -learning and prepare oneself to understand, select and apply appropriate techniques and modern engineering and IT tools to solve complex problems of digital systems field for environment and society context.

## **Programs Specific Outcomes (PSOs)**

- PSO-1 An ability to understand the issues and challenges related to advanced digital systems.
- PSO-2 An ability to solve complex digital systems problems, using latest hardware and software tools, along with analytical skills to achieve cost effective and appropriate solutions.
- PSO-3 Wisdom of social and environmental awareness along with ethical responsibility to have a successful career and to sustain passion and zeal for real-world applications using optimal resources as an entrepreneur.

Credit Courses					
Postgraduate Core (PC)	Postgraduate Elective (PE)				
Category	credits	Category	credits		
Maths (M)	4	Program Electives (PE)	16		
Program Core (PC)	22				
Minor Project (MP)	4				
Dissertation (D)	18				
Seminar	2				
Total	50	Total	16		
Grand Total 66 (minimum)					
Audit Courses					
Audit Course (Other Departments) (AC)	6				
Total	6				

The Overall Credit Structure for PG Programme

Category	Semesters	Ι	II	III	IV	Total
Maths (M)		4	-	-	-	4
Programme Core	(PC)	13	9	-	-	22
Program Electives	(PE)	-	8	8	-	16
Minor Project (MI	<b>)</b> )	-	-	4	-	4
Dissertation (D)				4	14	18
Seminar (S)		-	-	-	2	2
	Total	17	17	16	16	66

Credit Structure for M. Tech. in Digital Systems

## Department of Electronics and Communication Engineering M.M.M. University of Technology, Gorakhpur (U.P.)

## Curriculum for M.Tech. (Digital Systems)

## Junior year, Semester-I

Sr. No.	Category	Paper Code	Course Name	L-T-P	Credits
1.	М	MAS-112/ MMS-606	Advanced Engg. Mathematics	3-1-0	4
2.	PC	MEC-201	Advanced Digital Communication	3-1-2	5
3.	PC	MEC-101A	Advanced Microprocessor	3-0-2	5
4.	PC	MEC-102A	Nano CMOS Design Audit	3-1-0	4
				Total	18

## Junior year, Semester-II

Sr. No.	Category	Paper Code	Course Name	L-T-P	Credits
1.	PC	MEC-104	Embedded Systems Design	3-1-2	5
2.	PC	MEC-105	Digital Systems Design	3-1-0	4
3.	PE1	MEC-1**		3-1-0	4
4.	PE2	MEC-1**		3-1-0	4
			Audit		
				Total	17

## Senior year, Semester-III

	Category	Paper	Course Name	L-T-P	Credits
Sr.		Code			
No.					
1.	PE3	MEC-1**		3-1-0	4
2.	PE4	MEC-1**		3-1-0	4
3.	MP	MEC-120	Minor Project	0-0-8	4
4.	D	MEC-130	Dissertation Part-I	0-0-8	4
				Total	16

• Minor Project should be completed during the summer vacation after second semester.

## Senior year, Semester-IV

Sr. No.	Category	Paper Code	Course Name	L-T-P	Credits
1.	S	MEC-140	Seminar	0-0-4	2
2.	D	MEC-150	Dissertation Part-II	0-0-28	14
				Total	16

## Audit Course

S. No.	<b>Course Code</b>	Name of the Course	Prerequisite Subject	L-T-P	Credits
1.	BCS-01	Introduction to Computer	None	2-1-2	
		Programming			
2.	MCS-206	Information Security and	None	3-0-0	
		Cyber Laws			
3.	MBA 109	Research Methodology	None	3-0-1	

## Program Elective 1 & Program Elective 2

S.	Course	Name the Course	Prerequisite Subject	L-T-P	Credits
No.	Code				
1.	MEC-202	Advanced Digital Signal		3-1-0	4
		Processing			
2.	MEC-152	Digital Control Systems		3-1-0	4
3.	MEC-153A	Low Power CMOS Circuits		3-1-0	4
4.	MEC-154	Computer Aided Design of		3-1-0	4
		Electronics Circuits			
5.	MEC-155	Data and Computer		3-1-0	4
		Communication Networks			
6.	MEC-156	Digital Integrated Circuits		3-1-0	4
7.	MEC-157	Microcontrollers		3-1-0	4
8.	MEC-158	DSP Processors and		3-1-0	4
		Applications			
9.	MEC-159	RFIC		3-1-0	4
10.	MEC-160*	Fundamental of Nanoscale		3-1-0	4
		Transistors			

## **Program Elective 3 & Program Elective 4**

S.	Course	Name the Course	Prerequisite Subject	L-T-P	Credits
No.	Code				
1.	MEC-161	VLSI Testing		3-1-0	4
2.	MEC-162	Artificial Intelligence		3-1-0	4
3.	MEC-163	Neural Networks		3-1-0	4
4.	MEC-164	Virtual Instrumentation		3-1-0	4
5.	MEC-165	Digital Mobile		3-1-0	4
		Communication Systems			
6.	MEC-166	Optoelectronics Devices &		3-1-0	4
		Circuits			
7.	MEC-167	Organic Electronics Devices		3-1-0	4
		and Circuits			
8.	MEC-168	High Speed Devices and		3-1-0	4
		Circuits			
9.	MEC-169*	Introduction & Design of		3-1-0	4
		Photovoltaic Systems			

\* Subjects will be opted from session 2018-19.

## <u>SYLLABI</u>

## MMS 606 ADVANCED ENGINEERING MATHEMATICS

Course category	:	Basic Sciences & Maths (BSM)
Pre-requisites	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment methods</b>	:	Continuous assessment through tutorials, assignments, quizzes, One
		Minor and One Major Theory Examination.
Course Outcomes	:	The students are expected to be able to demonstrate the following
		knowledge, skills, and attitudes after completing this course

- 1. To find out the dimension of vector spaces
- 2. To describe the differences between finite-difference and finite-element methods for solving PDEs;
- 3. To solve Elliptical (Laplace/Poisson) PDEs using finite differences;
- 4. To solve functional using Euler method.

## **Topics Covered**

## **UNIT-I**

**Vector spaces and Linear transformation:** Vector spaces, subspaces, Linear dependence, Basis 9 and Dimension, Linear transformations, Kernel & images, matrix representation of linear transformation, change of basis, Eigen values and Eigen vectors of linear operators, diagonalization.

## UNIT-II

**Numerical Techniques:** Solution of algebraic and transcendental equations using bisection, Regula 9 Falsi and Newton Raphson's method, Numerical solution to linear system, LU factoring

decomposition, Cholesky method, Gauss Seidal method, Numerical eigen value problem, Jacobi, Givens method

## **UNIT-III**

**Calculus of Variation:** Functionals, Euler's equation and its generalization. One and several 9 independent variables. Initial value problems. Weierstrass's sufficiency condition for weak and strong minima and maxima

## UNIT-IV

**Numerical Solution of Partial Differential Equations**: Classification of partial differential 9 equations of the second order. Laplace equations and its solution by Liebmann's process. Poisson equation. Solution of Parabolic, Eliptic and Hyperbolic Equations. Applications to Engineering.

## Textbooks

- 1. K. Hoffman, R Kunze, Linear Algebra, Prentice Hall of India, 1971.
- 2. I. M. Gelfrand, S. V. Fomin, Calculus of Variation, Dover Publications.
- 3. M. D. Raisinghania, Advanced Differential Equations, Schand Publishers.
- 4. P. Kandasamy, K. Thilagavathy & K. Gunavathy, Numerical Methods, S. Chand Publ.

#### **MEC-201 Advanced Digital Communication**

<b>Course category</b>	: Program Core (PC)
Pre-requisite Subject	: NIL
<b>Contact hours/week</b>	: Lecture : 3, Tutorial : 1, Practical: 2
Number of Credits	: 5
<b>Course Assessment</b>	: Continuous assessment through tutorials, attendance,
methods	home
Course Outcomes	<ul> <li>assignments, quizzes, practical work, record, viva voce</li> <li>and minor and major theory &amp; practical Examination</li> <li>The students are expected to be able to demonstrate</li> </ul>
course outcomes	the following knowledge, skills and attitudes after completing
	this course

- 1. Understand basic components and representation of digital communication systems.
- 2. Design Optimum receivers with linear and decision-feedback equalizers.
- 3. Analyze performance of Multichannel, Multicarrier Systems and Spread Spectrum Signals

Analyse the digital communication system through Fading Multipath Channels. 4.

## **Topics** Covered

## UNIT I

Overview of Digital Communication: Digital communication system model. Sampling theorem, Communication channels, characteristics and Models, Signal space representations. Digitally modulated signals-Representations. Constellation diagram and design of transmitter and receiver for BPSK, QPSK, M-PSK, 16-QAM, FSK, MSK and GMSK and their BER performance analysis in AWGN channel.

## UNIT II

Communication Through Band-Limited Linear Filter Channels: Optimum receiver for channels with ISI and AWGN. Linear equalization, Decision feedback equalization, Turbo equalization, Self recovering equalization

## **UNIT III**

Multichannel, Multicarrier Systems and Spread Spectrum Signals: Model of Spread spectrum system. Direct sequence spread spectrum signals. Frequency -Hopped spread spectrum signals. Performance of spread spectrum system in jamming environment, Synchronization of spread spectrum signals.

## UNIT IV

Digital Communications through Fading Multipath Channels: Characterization and model. Frequency-Non selective, slowly fading channel, performance analysis of MRC, EGC, SC Diversity techniques over flat fading channel, Digital signalling over a frequency-selective, slowly fading channel, Coded waveforms for fading channel, Multiple access techniques, Capacity of multiple access methods, CDMA, Random access methods.

## **Experiments:**

1. Experiment on QPSK digital Modulation.

- 2. Experiment on M-ary QAM for different fading channels.
- 3. Analysis of Bit Error Rate (BER) for BPSK digital Modulation.
- 4. Analysis of Bit Error Rate (BER) for BFSK digital modulation
- 5. Analysis of BER for ASK digital modulation.

6. Study of ASK, PSK and FSK digital modulation using MATLAB.

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#### **Books & References:**

- 1. John G. Proakis, Digital Communications, 4/e, McGraw-Hill
- 2. Viterbi, A. J., and J. K. Omura, Principles of Digital Communication and Coding. NY: McGraw-Hill, 1979,ISBN: 0070675163.
- 3. Marvin K Simon, Sami M Hinedi, William C Lindsey Digital Communication Techniques Signal Design & Detection, PHI.
- 4. MIT OpenCourseWare, Electrical Engineering and Computer Science, Principles of Digital communication II, Spring 2006
- 5. Aazhang B. Digital Communication Systems (Connexions Web site). January 22, 2004. available at:http://cnx.rice.edu/content/col10134/1.3

## MEC-101A Advanced Microprocessors

<b>Course category</b>	: Program Core (PC)
Pre-requisite Subject	: NIL
<b>Contact hours/week</b>	: Lecture : 3, Tutorial : 1, Practical: 2
Number of Credits	: 5
<b>Course Assessment</b>	: Continuous assessment through three Viva voce, Practical
methods	work/record, attendance and Major Practical Examination
<b>Course Outcomes</b>	: After completion of this course the students are expected to be
	able to demonstrate following knowledge, skills and attitudes

- 1. Foster ability to understand and program the 16-bit microprocessors.
- 2. Ability to design 8086 based microprocessor system using different peripheral devices.
- 3. Ability to understand internal architecture and features of 32-bit Microprocessors.
- 4. Foster ability to understand the internal architecture and features of 64-bit Microprocessors.

#### **Topics Covered**

UNIT-I

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## 16-bit Processors:

Architecture, Signal Description, Physical Memory Organization, Bus-operation, Art of Assembly Language Programming (8086)

## UNIT-II

#### Programmable Peripherals, their working and Interfacing with 8086:

Programmable Peripheral Interface (8255 PPI), USART (8251), 8253/8254 Timer/counter, 8259 Interrupt Controller and 8257 DMA Controller

## UNIT-III

#### **32-bit Processors:**

Architecture, Addressing Modes, Real and Protected modes, Segmentation, Paging and Cache Management Unit

UNIT-IV

#### **Recent Advances in Microprocessors:**

Pentium: Salient Features and System Architecture, Branch Prediction, MMX Architecture, Overview of Pentium Pro, Pentium II, Pentium III and Pentium 4

## Experiments

- 1. Group-A: 8 Assembly Language programs based on 8086
- 2. Group-B : 4 Interfacing based experiments.
- Minimum 8 experiments must be performed during semester. Minimum 6 and 2 experiments should be performed from group-A and group-B respectively

#### **Books & References:**

1. AK Ray & MK Bhurchandi: "Advanced Microprocessors and Peripherals" - TMH

- 2. D.V.Hall, "Microprocessors and Interfacing" TMH
- 3. B. P. Singh & Renu Singh "Advanced Microprocessor & Microcontroller", New Age Publications.
- 4. V Rafiquzzaman: "Microprocessors and Applications" TMH

## MEC-102A Nano CMOS Design

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- Development of MOS technology in the last three decades and understand the essential process of Nano CMOS design.
- 2. Understand the electrical behavior of MOS transistors and design issues related to current MOS transistors used in digital circuits.
- 3. Understand the impact of device parameters on modern CMOS logic circuits in terms of power, area and switching behavior.
- Understand the physical design rules of nano CMOS circuits and study the modern Nano CMOS devices.

## **Topics Covered**

#### UNIT-I

CMOS Technology, ITRS Roadmap, Nano-CMOS Scaling Problems and Implications: Design Methodology in the Nano-CMOS Era, Innovations Needed to Continue Performance. CMOS Process Technology: n-well, p-well and twin-tub technology, Equipment Requirements for Front-End Processing

## UNIT-II

Electrical Behaviour of MOS transistor, SCE, Modelling of MOS transistor using SPICE: Various SPICE parameters, Model using Level-1 or Level-2 or any other advanced Level used by Industry

#### UNIT-III

CMOS Inverter Design; Supply Voltage Scaling in CMOS Inverters, Power and Area Considerations, Noise Margin, Effect of Threshold Voltage, Doping and Geometry Size on CMOS Switching Behavior

## UNIT-IV

Stick Diagrams; Physical Design Rules; Layout Designing; Euler's Rule, Bulk CMOS Design, SOI CMOS Design, PD- and FD-SOI CMOS Design, Solutions for Sub-threshold Leakage, Use of Highk, Leakage in CMOS Nanometric Technology

#### **Books & References:**

- 1. B.G. Streetman & S. Banerjee, "Solid State Electronic Devices", PHI.
- 2. S.M. Kang & Y. Leblibici, "CMOS Digital Integrated Circuits-Analysis & Design", TMH, Ed.
- 3. K. Eshraghian & Pucknell, "Introduction to VLSI", PHI
- 4. A. P. Chandrasekaran and R.W. Broadersen, "Low Power Digital CMOS Design", Wiley

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- 5. B. Razavi, "Design of Analog CMOS Integrated Circuits", TMH.
- 6. Research Papers from IEEE Transactions on Electron Devices, and Other Reputed Journals

#### **MEC-104 Embedded Systems Design**

Course category Pre-requisite Subject Contact hours/week Number of Credits Course Assessment	::	Program Core (PC) NIL Lecture: 3, Tutorial: 1, Practical: 0 4 Continuous assessment through tutorials, attendance, home
methods Course Outcomes	:	assignments, quizzes and Three Minor tests and One Major Theory Examination

- 1. To understand hardware and software design requirements of embedded systems.
- 2. To analyse the embedded systems' specification and develop software programs.
- 3. To evaluate the requirements of programming Embedded Systems, related software architectures and tool chain for Embedded Systems

#### **Topics Covered**

#### **UNIT-I**

Introduction to Embedded Systems: Definition of Embedded System, Embedded Systems Vs General Computing Systems, History of Embedded Systems, Classification, Major Application Areas, Purpose of Embedded Systems, Characteristics and Quality Attributes of Embedded Systems, Applications

#### **UNIT-II**

Embedded Processor: Devices & Architecture of 8051/89C51 Motorola, PIC, AVR, etc., Review of memory Architecture, I/O, Timer/ Counter & Interrupts

#### **UNIT-III**

RTOS Based Embedded & Task Communication: Operating System Basics, Types of Operating Systems, Tasks, Process and Threads, Multiprocessing and Multitasking, Task Scheduling, Shared Memory, Message Passing, Remote Procedure Call and Sockets, Task Synchronization: Task Communication/Synchronization Issues, Task Synchronization Techniques, Device Drivers, How to Choose an RTOS

#### **UNIT-IV**

Design & Tools: Design of an embedded application, Examples / Case Study

#### **Experiments:**

1. Embedded programming on 6713, TMS 320C6713/32 Embedded Trainer Kit

2. Embedded programming on 5410/16, TMS 320VC5410/16 Embedded Trainer Kit

## **Books & References:**

- Real-Time Systems and Programming Languages -Burns, Alan and Wellings, Andy, 2e, 1. (Addison-Wesley Longman), 1997
- 2. An Introduction to real time systems: Design to networking with C/C++ - Raymond J.A. Bhur and Donald L. Bialey (Prentice Hall), 1999
- 3. Real time Programming: A guide to 32 Bit Embedded Development- Grehan Moore, and Cyliax (AddisonWesley-Longman), 1998
- "Embedded Systems Design" Heath, Steve( Newnes), 1997 4.
- Embedded System Design: A Unified Hardware /Software Introduction Frank Vahid and 5.

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Tony Givargis, Wiley 2001

## MEC-105 Digital System Design

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Summarize various delays in combinational circuit and its optimization methods.
- 2. Design and implement hardware circuit to test performance and application.
- 3. To test the performance of digital memory devices in modern digital systems
- 4. Understand the architecture and use of microcontrollers for the basic operations and simulate using simulation software

Topics Covered UNIT-I

**Introduction:** Number System & Codes, Combinational logic circuits, Flip-Flops and related devices Digital Arithmetic operations and circuits counters and registers.

## UNIT-II

**Integrated Circuit Logic family**: Digital I.C. Terminology, TTL, ECL, MOS/CMOS logic families, IC interfacing, TTL driving CMOS & Vice Verso Low voltage Technology.

MSI Logic Circuits: Decoders/drivers, Encoders, Multiplexers, De-multiplexers, Magnitude Comparators, applications of MSI logic ICs.

## UNIT-III

**Memory Devices**: General memory operations, Programmable logic devices, Semi-conductor memories, SRAM, DRAM, expanding word size and capacity, special memory functions

## UNIT-IV

#### Introduction to Microprocessor & Micro-Computers:

Alphanumeric display devices, LCD and CRT Displays, Applications of programmable logic devices.

## Books & References:

- 1. R.J. Tocci: "Digital System: Principles & Applications" PHI
- 2. Manufacturers IC Data Sheet.

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## MEC-202 Advanced Digital Signal Processing

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Understand theory of multirate DSP and wavelets and capable of designing wavelet filters.
- 2. To be able to design prediction filters and understand solution of normal equation.
- 3. Estimate power spectrum of signals using different methods.
- 4. To study of basic wavelet transform methods

## **Topics Covered**

## UNIT-I

Basics of Multirate systems and its application, up sampling and Down - Sampling, Fractional Sampling rate converter. Polyphase decomposition. Efficient realisation of Multirate systems.Uniform filter banks and it's implementation using polyphase decomposition.

## UNIT-II

Two channel Quadrature Mirror Filter Banks, Perfect Reconstruction, M-channel PR QMFB.Time Frequency Analysis, Heisenberg's uncertinity principle. Short time fourier transform - Gabor transform. Continous Wavelet Tranform and it's properties. Multi Resolution Analysis, Discrete Wavelet Transform, Orthonormal Wavelet Analysis - Filterbank interpertation. Haar and Daubechise wavelets, Bi-orthogonal wavelets and Filter bank interpretation

## UNIT-III

B-Spline wavelets, Wavelet packets.2D wavelt transforms. Application of wavelet transform for data compression, noise reduction. Linear Prediction -Forward and Backward Prediction - Levinson-Durbin Algorithm, Schur Algorithm

## UNIT-IV

Power spectrum estimation of signals: Wide Sense Stationary Random Processes. Power spectral density. Non parametric methods: periodogram,Backman-Tuckey method. Parametric method: ARMA, AR processes, Yule-Walker method

## Books & References:

- 1. P. P. Vaidyanathan, Multirate Systems and Filterbanks, Prentice Hall
- 2. Wavelet Transforms Bopadikar and Rao, Pearson Education
- 3. Insight into wavelets, K. P. Soman, Prentice Hall India
- 4. Digital signal Processing, By John G. Proakis, Dimitris G. Manolakis, Pearson Education

## MEC-152 Digital Control System

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0

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Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Applications of sampling theorem in practical applications.
- 2. Develop the ability to test the observability and controllability
- 3. To design and test the compensator circuit.
- 4. Basic knowledge of the optimal control techniques

#### Topics Covered UNIT-I

Sampling Process & Control System: A/D & D/A conversion, Discrete System Modeling using Z-transform.

Discrete Control System Analysis Stability, Error-analysis, Bilinear Transformation, Frequency Response

## UNIT- II

**Discrete Transform Approximations:** Folding Aliasing, Transformations method (s,z and, w) Numerical Solution of Difference Equations.

Implementing Digital Control System: Control Logic, Software, Data flow Diagram, Real Time Design for Digital, Control. Real Time Scheduling

## UNIT-III

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**Compensator Design:** Cascade Compensation using Digitization Technique and Direct Techniques, Feedback Compensation Techniques, Software for Digital Controllers.

Basics of Modern Discrete Control Theory: System Structure, Controllability, Observability & State - Space stability.

## UNIT-IV

**Discrete Optimal Control:** Optimal Control Concepts, Maximum Principle, Discrete Linear <sup>9</sup> Regulator, Sampling Time.

## **Books & References:**

- 1. C. H. Houpis, Gray B. Lamont: "Digital Control Systems" McGraw-Hill.
- 2. I.J. Nagrath, M. Gopal: "Control System Engineering" New Age Publications

## MEC-153 Low Power CMOS Circuits

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4

<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Understand the overview of different logic families and their utility in low power CMOS circuits design.
- 2. Understand the static CMOS circuit design and study the impact of emerging low power approaches in CMOS circuit design.
- 3. Understand the different approaches of dynamic CMOS circuit design and its comparison with static CMOS circuit design in terms of performance parameters (power, area and switching behavior).
- 4. Study the different approaches of dynamic power reduction techniques in VLSI circuits and understand the design consideration of SRAM/DRAM cell

## Topics Covered UNIT-I

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Basics of MOS circuits: MOS Inverters, MOS Combinational Circuits - Different Logic Families, Static & Dynamic Circuits

## UNIT- II

Combinational Logic Designs using CMOS, Emerging low power approaches, Design using CMOS TG, Calculations of Delay & Power Dissipation of CMOS inverter Circuits

## UNIT-III

Dynamic Logic Circuits: Basic Principles of Pass Transistor Circuits, Voltage Bootstrapping, Dynamic CMOS Circuit Techniques: Dynamic Dissipation in CMOS, High Performance CMOS Circuits: Domino & NORA CMOS Logic.

## UNIT-IV

Circuit Techniques for Dynamic Power Reduction: Approaches for Power Reduction, Dynamic Power Consumption Component, Circuit Parallelization, and Voltage Scaling based Circuit Techniques Memory Design: SRAM & DRAM Cells, Noise Margin Calculations, Full CMOS SRAM Cells: Leakage Currents, Read/Write operations

## Books & References:

- 1. S.M. Kang & Y. Leblibici, "CMOS Digital Integrated Circuits-Analysis & Design", TMH, Ed.
- 2. K. Eshraghian&Pucknell, "Introduction to VLSI", PHI.
- 3. A.P.Chandrasekaran and R.W.Broadersen, "Low Power Digital CMOS design", Wiley
- Christian Piguet, "Low Power CMOS Circuit: Technology, Logic Design & CAD Tools", Taylor & Francis
- 5. Gary Yeap, "Practical Low Power Digital VLSI design", Kluwer
- 6. J.M. Rabaey, "Digital Integrated Circuits-A Design Perspective", PHI

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## MEC-154 Computer Aided Design of Electronic circuits

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Learn the CAD Tools, SPICE simulation and HDL and Verilog
- 2. Modelling and characterization of semiconductor devices
- 3. To design and simulate HDL and Verilog based circuit on FPGA kit
- 4. To study of CAD tool

## **Topics** Covered

## UNIT-I

Modelling analogies, and their role, Introduction to general purpose analog computer and its applications in simulation of linear and non-linear systems, CAD Tools, Importance of SPICE simulation, Introduction to HDL and verilog

## UNIT-II

Modelling & Simulation of Semiconductor Devices to predict its electrical behaviour, SPICE parameter of MOS and BJT, Simulation of MOS and BJT based circuits

## UNIT-III

Digital Computer Simulation of Electrical and Electronic Circuits, Application of HDL and verilog for digital circuit simulation, Verification mechanism in design flow

## UNIT-IV

Various CAD tools for front end and back-end design, CAD tools for layout generation, CAD tools for testing and verification of ICs

## **Books & References:**

- 1. Neil Weste: "Principle of CMOS Design" Addison Wesley
- 2. Rashid: "Spice for Circuits of Electronics using PSpice"- Prentice-Hall
- 3. Banafsheh Rezaeian, "Simulation and Verification Methodology of Mixed Signal Automotive ICs" November 22, 2012

## MEC-155 Data and Computer Communication Networks

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
<b>Contact hours/week</b>	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory

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Course Outcomes	:	Examination The students are expected to be able to demonstrate the following knowledge, skills and attitudes after completing this course

- 1. Build an understanding of the fundamental concepts of Networking and data transmission protocols.
- 2. Understand the design and implementation of networks.
- 3. Know about how to measure and trouble shoot the performance of network.
- 4. Awareness with cellular mobile computer communication.

## Topics Covered UNIT-I

LAN Networking & Data Transmission Protocols: IP, IPX, Apple-Talk, Ethernet, FDDI, Token Ring, Wireless 802.11b

WAN Digital Transmission Technologies: T-Carrier, SONET, Frame Relay ISDN, Global Cellular.

## UNIT-II

#### Design & Implementation of Enterprise- Networks.

Routers & Switches (including ATM Switches), Router configuration Multiprotocol Network Traffic Routing in PDN & Internet Environments.

#### UNIT-III

Network Performance Measurement & Trouble Shooting Concepts : including SNMP.

#### UNIT-IV

**Cellular Mobile Computer Communication**: GSM Technology, NA-TDM, PCN VoIP/FoIP & SMS, CISCO's IGRP /EIGRP, ACL NAT, TUNNELING & IOS basics.

Satellite Links & Broad Band ISDN Network.

#### **Books & References:**

- 1. M James Martin: "Understanding the Network" Techmedia Publications.
- 2. William Stallings: "Data & Computer Communication" Pearson Education
- 3. William C. Y. Lee: "Mobile Cellular Tele Communication" McGraw Hill

## MEC-156 Digital Integrated Circuits

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination

#### **Course Outcomes** : The students are expected to be able to demonstrate the following knowledge, skills and attitudes after completing this course

- 1. To understand about modelling of various semiconductor devices.
- 2. To get complete understanding about different digital logic circuits.
- 3. To Know various CMOS logics and their design aspects.
- 4. To get complete knowledge about different types of memories.

## **Topics Covered**

## UNIT-I

Semiconductor Components of Digital Integrated Circuits: Modelling of PN Junction Diodes, BJTs, and MOSFETs, Model Parameter Extraction of these devices

## **UNIT-II**

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BJT Inverters DC and Switching Characteristics, Schottky Transistor Specifications of Logic Circuits, Qualitative discussion on TTL Circuits, Standard TTL Circuits, Advanced TTL Circuits, I-square L Technology, Edge triggered D-F/F, I-square L-Condition for Proper Operation, Schottky Transistor Logic, Stacked I-square L, ECL Basic Operation

## UNIT-III

nMOS Logic Circuits, nMOS inverters; CMOS inverters, MOS NAND,NOR and Other Gates: Clocked CMOS, Dynamic CMOS, Transmission Gates; Realization Of MUX, decoder, D-F/F **BiCMOS Gates**, **BiCMOS Driver** 

## UNIT-IV

9 Memories: Types of Memory, Static and dynamic Memories, BiCMOS SRAM-DRAM, CMOS and BiCMOS ROM-EPROM, EEPROM and Flash EPROM

## **Books & References:**

- 1. Digital Integrated Circuits By Rabaey, Jan, Anantha Chandrakasan, and Bora Nikolic, Prentice Hall Publications.
- 3. CMOS Digital Integrated Circuits By Kang and Leblebici, TMH Publications

#### **MEC-157 Microcontrollers**

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Analyse and introduce the basics of embedded systems and embedded microcontroller cores.
- 2. Understand the basics of 8051 microcontroller and interfacing devices.
- 3. Understand assembly language program for 8051
- 4. Basic understanding of advanced microcontrollers like, AVR, MCS-96, and ARM microcontrollers.

#### **Topics Covered**

## UNIT-I

**Introduction to Embedded Systems:** Overview of Embedded System Architecture, Application areas, Categories of embedded systems, specialties of embedded systems. Recent trends in embedded systems. Brief introduction to embedded microcontroller cores CISC, RISC, ARM, DSP and SoC

#### UNIT-II

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**8051** Microcontroller: Introduction to 8051 Microcontroller, Architecture, Pin configuration, Memory organization, Input /Output Ports, Counter and Timers, Serial communication, Interrupts.

#### UNIT-III

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Assembly Language Programming of 8051: Instruction set, Addressing modes, Development tools, Assembler Directives, Programming based on Arithmetic & Logical operations, I/O parallel and serial ports, Timers & Counters, and ISR

## UNIT-IV

Advanced Microcontrollers: AVR, MCS-96 and ARM Microcontrollers: Important Features, Pins and Signals Description, Architectures, memory organization etc.

## **Books & References:**

- 1. The 8051 microcontroller & Embedded systems, M. A. Mazidi, J. G. Mazidi, R. D. McKinlay, Pearson
- 2. The 8051 microcontroller & Embedded systems, Kenneth J. Ayala, Dhananjay V. Gadre, Cengage Learning
- Embedded / real time systems: concepts, design & programming, Black Book, Dr. K. V. K. K. Prasad, Dreamtech press, Reprint edition 2013
- 4. Introduction to embedded systems, Shibu K. V., McGraw

## MEC-158 DSP Processors and Applications

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Build idea about issues involved in DSP processor design in terms of speed, cost, quantization error, and some other parameters.
- 2. Understand the key DSP hardware elements, DSP processor, and its architecture.
- 3. Identify software development tools like, assembler, linker, and simulator.

4. Develop idea for the applications of DSP processors in the spectral analysis, filters, linear predictive coding, imaging, and instrumentation.

Topics Covered	
UNIT-I	9
Review of DSP fundamentals	
Issues involved in DSP processor design – speed, cost, accuracy, pipelining parallelism, Quantization error, etc.	
Unit-II	9
Key DSP hardware elements – Multiplier, ALU, Shifter, Address generator, etc.	
DSP Processor and Architecture - Texas, ADSP and Motorola DSP chips, Architecture, Instruction	
sets.	
UNIT-III	9
Software development tools – Assembler, Linker, and Simulator.	
UNIT-IV	9
Applications using DSP processors – Spectral analysis, FIR / IIR filters, Linear Predictive Coding, Imaging, Instrumentation, etc.	7
Books & References:	
DOURS & REFERENCES:	

- 1. K Padmanabhan, S Ananthi & RV Rajeshwaran: "Practical Approach to Digital Signal Processing"
- 2. TMS Data Manual
- 3. ADSP Data Manual
- 4. Motorola Data Manual
- 5. Rabiner LR & Gold B: "Theory and Application of Digital Signal Processing" PHI, 1996.

## MEC-159 RFIC

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
<b>Contact hours/week</b>	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Introduce with RF and wireless technology with related applications and design issues.
- 2. Acquire the basic knowledge of LNA technologies, topologies, and the layout of cascade devices.
- 3. Analyse general considerations and performance parameters of mixers and oscillators.
- 4. To get idea about different power amplifiers, and RF transceiver design.

**Topics Covered** 

## UNIT-I

Introduction to RF and Wireless Technology: Complexity comparison, Design bottle necks, Applications, Issues in RF Design: Noise, Linearity and Signals

## Unit-II

Basics of LNA technologies, LNA topologies, CS stage with inductive load, Resistive feedback, Alternative LNA technologies, layout of cascade devices

## UNIT-III

Mixers and Oscillators: General Considerations and Performance Parameter of Mixer circuit, Up & Down Conversion Mixers, Cascaded Stages, oscillators, Frequency synthesizers

## UNIT-IV

Power Amplifiers: General considerations, Classification, High Frequency Power Amplifiers, large signal impedance matching, linearization techniques.

On-chip Passive Devices and integrated passive devices used in RF transceiver design

## **Books & References:**

- 1. Behzad Razavi, RF Microelectronics Prentice Hall of India, 2001.
- 2. Thomas H. Lee, The Design of CMOS Radio Integrated Circuits, Cambridge University Press
- 3. John W. M. Rogers and Calvin Plett, "Radio Frequency Integrated Circuit Design" Second Edition, Artec House Publication

## MEC-160 Fundamental of Nanoscale Transistors

Course category	:	Program Core (PC)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Understanding basic concepts of distribution functions, density of states, NEGF formalism, and scattering theory of MOSFET.
- 2. Introduce characteristics and physical view of MOSFET, and ballistic MOSFET.
- 3. Introducing various nanowire filed effect transistors.
- 4. Analysing Graphene nanoribbons field effect transistor, and Transition Metal Dichalcogenides Field Effect Transistors.

## **Topics** Covered

#### UNIT-I

Basic Concepts: Distribution functions.1D, 2D, and 3D Carriers, Density of states and carrier densities, Diffusive and Ballistic transport, The NEGF formalism, Scattering theory of MOSFET.

#### Unit-II

Introduction to MOSFET,1D and 2D MOS Electrostatics, Current-Voltage characteristics of MOSFET, Physical view of the nanoscale MOSFETs, The ballistic MOSFET, Ballistic MOSFET under nondegenerate and degenerate conditions.

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## UNIT-III

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Nanowire Field Effect Transistors: Introduction, Silicon nanowire MOSFETs, The I-V characteristics for nondegenerate and degenerate carrier statistics, Carbon nanotubes, Carbon nanotube MOSFETs and its characteristics.

## UNIT-IV

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Introduction to Graphene Nanoribbons Field Effect Transistors(GNRFETs), Transfer and output characteristics of GNRFETs, Introduction to Transition Metal DichalcogenidesField Effect Transistors(TMDFETs), Transfer and output characteristics of TMDFETs.

## **Books & References:**

- 1. Mark S. Lundstrom, Nanoscale Transistors, Springer.
- SupriyoDatta, Lessons fromNanoelectronics: A New Perspective on Transport— Part A: Basic Concepts, 2<sup>nd</sup> Ed, World Scientific Publication.
- 3. Website for Online Video "www.nanohub.org"

## MEC-161 VLSI Testing

Course category	:	Programme Elective (PE)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Analyse the use of procedural statements and routines in testbench design with Digital and Analog VLSI Testing, VLSI Technology Trends Affecting Testing.
- 2. Analyse the various test generation methods for static & dynamic VLSI Testing.
- 3. Tackle the problems associated with testing of semiconductor circuits at earlier design levels so as to significantly reduce the testing costs.
- 4. Understand test data analysis and defect level estimation.

#### **Topics Covered**

## UNIT-I

Testing Philosophy, Role of Testing, Digital and Analog VLSI Testing, VLSI Technology Trends Affecting Testing

#### UNIT-II

Techniques for Testing Chips, Types of Testing, Automatic Test Equipment, Multi-Site Testing, Electrical Parametric Testing

#### UNIT-III

Test Economics, Defining Costs, Production, Benefit-Cost Analysis, Economics of Testable Design, Yield, Defect Level as a Quality Measure

#### **UNIT-IV**

Test Data Analysis, Defect Level Estimation, Defects, Errors, and Faults, Functional Versus Structural Testing, Fault Models

#### Books & References:

- 1. M.L. Bushnell and V.D. Agrawal, "Essentials of Electronic Testing", Kluwer Academic Publishers, 2000.
- 2. M. Abramovici, M.A. Breuer and A.D. Friedman, "Digital Systems Testing and Testable Design", Wiley-IEEE Press, 1993.
- 3. N.K. Jha and S. Gupta, "Testing of Digital Systems", Cambridge University Press, 2004
- 4. L. T. Wang, C-W. Wu and X. Wen, "VLSI Test Principles and Architectures", Morgan Kaufman Publishers, 2006
- 6. P.H. Bardell, W.H. McAnney and J. Savir, "Built-in Test for VLSI: Pseudorandom Techniques", Wiley Interscience, 1987

## MEC-162 Artificial Intelligence

Course category	:	Program Elective (PE)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Analyse the fundamental understanding of the history of artificial intelligence (AI) and its foundations.
- 2. Apply basic principles of AI in solutions that require problem solving, inference, perception, knowledge representation, and learning.
- 3. Understand the various applications of AI techniques in intelligent agents, expert systems.
- 4. Demonstrate proficiency developing applications in an 'AI language', expert system shell, or datamining tool such as Fuzzy logic

## **Topics Covered**

#### UNIT-I

The concept of AI, Approaches to AI, Brief History of AI, An overview of AI, Introduction to Artificial Neural Networks, ES

#### UNIT-II

Reactive Machines: Perception and Action, Representing and Implementing Action Functions, ANN Models, Gradient Decent Methods, The Widrow-Hoff Procedure, Generalized Delta Rule, Back Propagation, Hopefield and Kohenen's Net

## UNIT-III

Search in State Spaces: State space approach, State Space Graph, Depth First, Breadth First Search, Iterative Deepening, Backtracking, Heuristic Search, A\* algorithm, Heuristic Functions and Search Efficiency, Approximate Searches, Learning Heuristic Functions

#### UNIT-IV

Fuzzy Logic: Fuzzy Sets, Fuzzy operations, Membership functions, Fuzzification, Fuzzy decision making, Fuzzy classification, clustering, c- means algorithm, Genetic Algorithm

#### **Books & References:**

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- 1. Nilson N J: "Artificial Intelligence: A new synthesis" Morgan Kaufmann Publishers, 1998
- 2. Timothy J Ross: "Fuzzy Logic with Engineering Applications" MGH, 1995
- 3. Rich E, and Knight K: "Artificial Intelligence" MGH, 1992
- 4. Patterson, D W: "Introduction to AI and Expert Systems" PHI, 1992
- 5. George J Klir, Bo Yuan: "Fuzzy Sets and Fuzzy Logic Theory and Applications" PHI, 1995
- 6. B. Yegnanarayana: "Artifical Neural Networks" PHI

## MEC-163 Neural Networks

Course category	:	Program Elective (PE)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Learn the concept of Neural Networks and its subsystems like ANN, learning concepts, neuron models
- 2. Understand basic of Hop field model and different types of learning models
- 3. Learn the concept of radial basis function and its learning laws and counter propagation networks
- 4. Analyze the applications of neural networks

## **Topics Covered**

#### UNIT-I

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Neural networks characteristics, History of development in neural networks principles, Artificial neural net terminology, Model of a neuron, Topology, Learning, types of learning, Supervised, Unsupervised and Reinforcement learning, Knowledge representation and acquisition.

#### **UNIT-II**

Basic Hop field model, Basic learning laws, Unsupervised learning, Competitive learning, K-means clustering algorithm, Kohonen's feature maps.

## UNIT-III

Radial basis function neural networks, Basic learning laws in RBF nets, Recurrent back propagation, Introduction to counter propagation networks, CMAC network, and ART networks.

#### UNIT-IV

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Applications of neural nets such as pattern recognition, Optimization, associative memories, speech and decision making. VLSI implementation of neural networks

#### **Books & References:**

- 1. J.M. Zurada: "Introduction to artificial neural systems"- Jaico Pub,2009
- 2. Simon Haykin : "Neural Networks"- PH, 1999

## MEC-164 Virtual Instrumentation

**Course category** 

rtual instrumentation

Program Elective (PE)

Pre-requisite Subject	:	NIL
<b>Contact hours/week</b>	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

1. Understand fundamentals of virtual instrumentation

2. Understand the concepts of graphical programming

3. Represent and review signals in digital domain

4. Identify the analysing tools and simple programming of them.

## **Topics Covered**

## UNIT-I

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Historical perspective, advantages, Block diagram, Architecture o f a Virtual Instrument, Data Flow Techniques, Graphical programming in data flow, comparison with Conventional programming

## UNIT-II

VIS and sub-VIS, loops and charts, arrays, clusters and graphs, case and sequence structures, formula nodes, local and global variables, string and file I/O

## UNIT-III

ADC, DAC, DIO, counters & timers, PC Hardware structure, timing, Interrupts DMA, software and hardware installation.

## UNIT-IV

Current loop, RS 232C/ RS485, GPIB, System buses, interface buses: USB, PCMCIA,VXI, SCXI, PXI, etc., networking basics for office & Industrial applications, VISA and IVI, Image Acquisition and Processing. Motion control

## **Books & References:**

- 1. Jerome, Jovitha: "Virtual Instrumentation and LABVIEW", PHI Learning, New Delhi, 1<sup>st</sup> Edition, 2010
- 2. Sanjay Gupta and Joseph John: "Virtual Instrumentation Using Lab View", Tata McGraw Hill, New Delhi,1st Edition, 2008
- 3. Ronald W. Larsen: "LabVIEW for Engineers", Prentice Hall Ltd, USA Jan 2010
- 4. LabVIEW: Basics I & II Manual, National Instruments, 2005

## MEC-165 Digital Mobile Communication System

Course category	:	Program Elective (PE)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination

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<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Analyse and understand the various multiple access techniques in digital mobile communication system
- 2. understand the concept of spread spectrum communication system
- 3. Apply the concept of GSM in real time applications
- 4. Identify the electronic navigation & surveillance systems

#### **Topics Covered**

## UNIT-I

TDMA, classical ALOHA, Slotted ALOHA, Carrier Sense Multiple Access, Demand Assigned Multiple Access

#### UNIT-II

Spread Spectrum Techniques: Introduction, Fundamental Concepts, pseudo noise sequences, CDMA, FHSS, DSSS, Synchronization of Spread Spectrum, Spread Spectrum applications in cellular communication, PCs, and mobile communication

## UNIT-III

GSM: Mobile Services, System Architecture, Radio interface, Protocols, localization and calling, Handover, Security, and New Data Services

#### **UNIT-IV**

Electronic navigation & surveillance Systems, Blue tooth, GPS, Global Mobile Satellite Systems

#### **Books & References:**

- 1. Dr. Kamilo Feher: "Wireless Digital Communications", PHI
- 2. Jochen Schiller: "Mobile Communications", Pearson Education
- 5. Raj Pandya: "Mobile and Personal Communication Systems and Services", IEEE Press, PHI

## MEC-166 Optoelectronic Devices & Circuits

Course category	:	Program Elective (PE)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Explain the fundamental concepts of optoelectronic devices and its position in modern physics.
- 2. Demonstrate accurate and efficient use of semiconductor materials.
- 3. Compare the structural characteristics of different optical devices and the different fabrication processes.1.

**Topics Covered** 

## UNIT-I

Elemental and Compound Semiconductor, Electronic Properties of Semiconductor: Carrier Effective masses and band structure, effect of temperature and pressure on bandgap, Carrier scattering phenomena, conductance processes in semiconductor, bulk and surface recombination phenomena

UNIT-II

Optical Properties of Semiconductor, EHP formation and recombination, absorption in semiconductors, Effect of electric field on absorption, absorption in quantum wells, radiation in semiconductors, deep level transitions, Augur recombination

## UNIT-III

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Junction theory, Schottky barrier and ohmic contacts, semiconductor hetero junctions, LEDs, Photo detectors, Solar Cells

## UNIT-IV

Optoelectronics modulation and switching devices: Analog and Digital modulation, Franz-Keldysh and Stark effects modulators, Electro-optic modulators.

Optoelectronics Integrated Circuits (OEICs): Need for hybrid and monolithic integration, OEIC transmitters and receivers

#### **Books & References:**

- 1. Pallab Bhattachrya: "Semiconductor Optoelectronic Devices", Prentice Hall Publications, 1997
- 2. S.M. Sze, "Physics of Semiconductor Devices", Wiley Publications, 2000

## MEC-167 Organic Electronics Devices and Circuits

Course category	:	Program Elective (PE)
Pre-requisite Subject	:	NIL
<b>Contact hours/week</b>	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

1. Ability to analyse organic material, polymer, and semiconductor. Merit and demerits of inorganic semiconductors.

Ability to analyse Organic Thin Film Transistors (OTFTs) and Modelling of Organic Devices.
 Ability to describe the behaviour of Organic Light Emitting Diodes (OLEDs) and Organic Solar Cells.
 Ability to describe the Organic Thin Film Transistors Applications.

#### **Topics Covered**

UNIT-I

#### **Organic Materials and Device Physics:**

Introduction; Organic Materials: Conducting Polymers and Small molecules, Organic Semiconductors: p-type and n-type semiconductors, Source, Drain and Gate Electrodes, Gate Dielectrics, Substrate; Concept of Charge Transport in Organic Semiconductors; Energy Band Diagram; Comparison between Organic and Inorganic Semiconductors including the Merits, Demerits and Limitations

#### UNIT-II

## Organic Thin Film Transistors (OTFTs) and Modeling of Organic Devices:

Introduction; Operating Principle; Classification of Various OTFT Structures; Output and Transfer Characteristics; Performance Parameters; Extraction of Performance Parameters, Impact of Structural

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Parameters on Behavior of OTFT; Merits, Demerits and Limitations of Organic Devices; Effect of Self Assemble Monolayer (SAM); Different OTFT Models; Stability Issues, Future Scope. Various Defects and Effects in Organic Devices; Modeling of OTFT Structures; Concept of Contact Resistance: Origin of Contact Resistance, Contact Resistance Extraction, Analysis and Performance Parameters Comparison of OTFT structures; Single Gate (SG) and Dual Gate (DG) OTFT Performance Comparison

## UNIT-III

## Organic Light Emitting Diodes (OLEDs) and Organic Solar Cells:

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**OLED**: Introduction; Organic Materials for OLEDs; Classification of OLEDs, Operating Principle; Output and Transfer Characteristics; Analysis of OLED Performance: Optical, Electrical and Thermal properties, Merits and Demerits; Stability Issues; OLEDs as display Applications. **Organic Solar Cell**: Introduction; Materials for organic Solar Cells; Operating Principle; Characteristics, Applications and Future Scope.

UNIT-IV

## **OTFT Applications:**

**Organic Digital Circuits:** All *p*-Type, Hybrid Complementary Inverters, Fully Organic Complementary Inverter Circuits and Their Comparison; Logic Circuit Implementation. **Organic Memory:** Organic Static Random Access Memory (OSRAM) and other Important Organic Memory Designs.

## **Books & References:**

- 1. Hagen Klauk, Organic Electronics: Materials, Manufacturing and Applications, Wiley-VCH Verlag Gmbh & Co. KGaA, Germany, 2006
- 2. Klaus Mullen, Ullrich Scherf, Organic Light Emitting Devices: Synthesis, Properties and Applications, Wiley-VCH Verlag Gmbh & Co. KGaA, Germany, 2005
- 3. Hagen Klauk, Organic Electronics II: More Materials and Applications, Wiley-VCH Verlag Gmbh & Co. KGaA, Weinheim, Germany, 2012
- 4. Flora Li, Arokia Nathan, Yiliang Wu, Beng S. Ong, Organic Thin Film Transistor Integration: A Hybrid Approach, Wiley-VCH, Germany; 1<sup>st</sup> Ed., 2011
- 5. Wolfgang Brutting, Physics of Organic Semiconductors, Wiley-VCH Verlag Gmbh & Co. KGaA, Germany, 2005
- 6. IEEE Transaction on Electronic Devices, Organic Electronics Devices and Circuits based Thesis

## MEC-168 High Speed Devices and Circuits

Course category	:	Program Elective (PE)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
Course Outcomes	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

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- 1. To understand and draw the characteristics of semiconductor materials
- 2. Modelling and characterization of high-speed GaAs based device
- 3. To study of V-I characteristics of MESFET
- 4. Performance study of HEMT and SiGe HBT based devices

## **Topics Covered**

## UNIT-I

Introduction to Basic Concepts, Requirements of High Speed Devices, Circuits & Materials Semiconductors, Ternary Compound Semiconductor and their Application, Crystal Structures in GaAs, Dopants and impurities in GaAs and InP

UNIT-II

Brief Overview of GaAs Technology for High Speed, GaAs and InP Devices for Microelectronics, Ohmic Contacts on Semiconductors, Fermi Level Pinning & Schottky Barrier Diodes

#### UNIT-III

Metal Semiconductor contacts for MESFET, MESFET Operation & I-V Characteristics

#### **UNIT-IV**

Hetero Junctions & HEMT, HEMT 1-V Characteristics and Transconductance, SiGe Technology, SiGe HBT

## Books & References:

- 1. S.M. Sze, "High Speed Semiconductor Devices", Wiley
- 2. Michael Shur, "GaAs Devices and Circuits", Plenum Press
- 3. C.Y. Chang and F. Kat, "Gallium Arsenide High Speed Devices: Physics Technology and Circuit Applications", Wiley
- 7. H. Beneking, "High Speed Semiconductor Devices: Circuit Aspects and Fundamental Behavior", Chapman and Hall, LONDON

## MEC-169 Introduction & Design of Photovoltaic Systems

Course category	:	Program Elective (PE)
Pre-requisite Subject	:	NIL
Contact hours/week	:	Lecture: 3, Tutorial: 1, Practical: 0
Number of Credits	:	4
<b>Course Assessment</b>	:	Continuous assessment through tutorials, attendance, home
methods		assignments, quizzes and Three Minor tests and One Major
		Theory
		Examination
<b>Course Outcomes</b>	:	The students are expected to be able to demonstrate the
		following knowledge, skills and attitudes after completing
		this course

- 1. Ability to describe the different parameters of photovoltaic cell, general design tools used for PV cell.
- 2. Ability to understand Series and Parallel Interconnection, Energy From Sun, Incident Energy Estimation.
- 3. Ability to describe the Sizing of PV cell, MPPT concept, MPPT algorithms, PV-Battery Interfaces: Direct PV-battery connection, Charge controller.
- 4. Ability to describe the Peltier device-principle, PV and Water Pumping, AC to DC transformations, DC to AC transformations.

## Topics Covered UNIT-I

Evolution of the Photovoltaic cell, PV cell characteristics and equivalent circuit, Model of PV cell,

Short Circuit, Open Circuit and peak power parameters, Cell efficiency, Effect of temperature, Fill factor, General design tools used for PV cell.

#### UNIT-II

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Series and Parallel Interconnection: Identical and Non-identical cells in series and parallel, Protecting cells in series and parallel. Energy From Sun: Insolation and irradiance, Solar geometry, Sunrise and sunset hour angles. Incident Energy Estimation: Energy on a tilted flat plate, Atmospheric effects, Air Mass, Energy with atmospheric effects, and Clearness index.

#### UNIT-III

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Sizing of PV cell: Sizing PV for applications without batteries, Batteries - Capacity, C-rate, Efficiency, Battery selection, Batteries in series and parallel configurations. PV system design-Load profile, Days of autonomy and recharge, Battery size, PV array size, MPPT concept, MPPT algorithms, PV-Battery Interfaces: Direct PV-battery connection, Charge controller.

## UNIT-IV

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Peltier device-principle, Peltier element, Peltier cooling, Thermal aspects- Conduction, Convection, A peltier refrigeration example. PV and Water Pumping: Water pumping principle, Hydraulic energy and power. PV-Grid Interface:Grid connection principle, PV to grid topologies, AC to DC transformations, DC to AC transformations.

## Books & References:

- Augustin M C Evoy, Tom Markvart, Luis Castañer "Practical Handbook of Photovoltaics Fundamentals and Applications," 2<sup>nd</sup>Edn. Elesvier.
- 2. Chenming, H. and White, R.M., Solar Cells from B to Advanced Systems, McGraw Hill Book Co, 1983
- 3. Ruschenbach, HS, Solar Cell Array Design Hand Varmostrand, Reinhold, NY, 1980
- 8. Proceedings of IEEE Photovoltaics Specialists Conferences, Solar Energy Journal.